

# EV Group

## Advanced Packaging and 3D Interconnect

GENERAL

BENEFITS

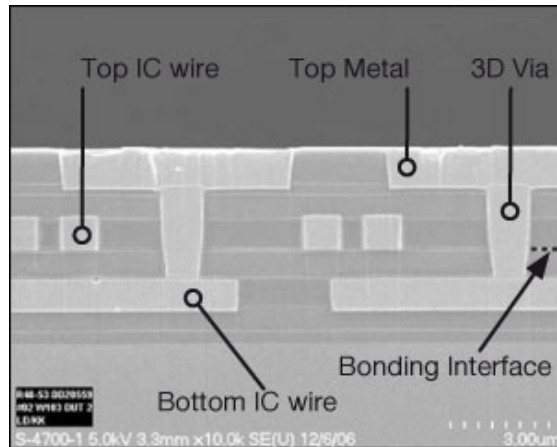
Solutions for the semiconductor and related microelectronics industries.

**EVG GEMINI:** The only field-proven automated production wafer bonder for 3D integration in the semiconductor industry designed for processing wafer sizes up to 300mm with maximum flexibility.

- Void-free bonding with sub-micron to micron-level alignment accuracy
- Easy conversion to different wafer sizes
- Modular design with a minimized footprint



GEMINI® Automated Production Wafer Bonder



CEA Liti - MINATEC / Alliance, SiO<sub>2</sub> bonding, pitch ~51m (SOI)

### Triple i - the key to your success



**Invent**

**Innovate**

**Implement**

There are no limits; only limiting thoughts

Innovation is dedication and superior competence

Reliability is the demand. Consistently high, trustworthy performance is our response

**You would like to enlarge your profit?**

For more information please contact: [3Dinterconnect@EVGroup.com](mailto:3Dinterconnect@EVGroup.com)

**EV Group (EVG)** is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through its flexible manufacturing model, EVG develops reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customer's fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection equipment.

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